

CMXD2004

**SURFACE MOUNT
TRIPLE ISOLATED
HIGH VOLTAGE
SILICON SWITCHING DIODES**



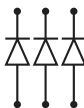
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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMXD2004 type contains three (3) Isolated High Voltage Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a SUPERmini™ surface mount package, designed for applications requiring high voltage capability.

MARKING CODE: X04

SUPERmini™



SOT-26 CASE

MAXIMUM RATINGS: (T_A=25°C)

Continuous Reverse Voltage
 Peak Repetitive Reverse Voltage
 Average Forward Current
 Continuous Forward Current
 Peak Repetitive Forward Current
 Peak Forward Surge Current, tp=1.0µs
 Peak Forward Surge Current, tp=1.0s
 Power Dissipation
 Operating and Storage Junction Temperature
 Thermal Resistance

SYMBOL

V_R 240
 V_{RRM} 300
 I_O 200
 I_F 225
 I_{FRM} 625
 I_{FSM} 4.0
 I_{FSM} 1.0
 P_D 350
 T_J, T_{stg} -65 to +150
 Θ_{JA} 357

UNITS

V
 V
 mA
 mA
 mA
 A
 A
 mW
 °C
 °C/W

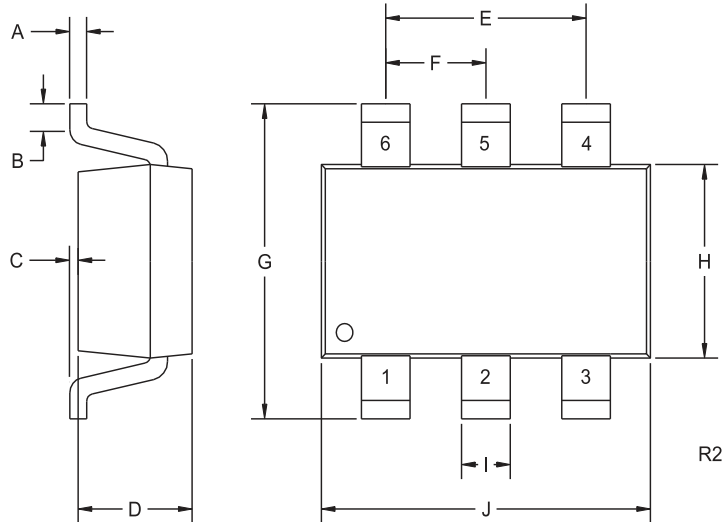
ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNIT
I _R	V _R =240V		100	nA
I _R	V _R =240V, T _A =150°C		100	µA
BV _R	I _R =100µA	300		V
V _F	I _F =100mA		1.0	V
C _T	V _R =0, f=1.0MHz		5.0	pF
t _{rr}	I _F =I _R =30mA, I _{rr} =3.0mA, R _L =100Ω		50	ns

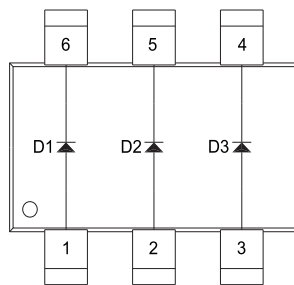
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SOT-26 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.004	0.007	0.11	0.19
B	0.016	-	0.40	-
C	-	0.004	-	0.10
D	0.039	0.047	1.00	1.20
E	0.074	0.075	1.88	1.92
F	0.037	0.038	0.93	0.97
G	0.102	0.118	2.60	3.00
H	0.059	0.067	1.50	1.70
I	0.016		0.41	
J	0.110	0.118	2.80	3.00

SOT-26 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

MARKING CODE: X04

R4 (9-February 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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